

Title (en)
SEMICONDUCTOR DEVICE PACKAGE

Title (de)
HALBLEITERBAUELEMENTGEHÄUSE

Title (fr)
CONDITIONNEMENT DE DISPOSITIF À SEMICONDUCTEUR

Publication
EP 3451396 B1 20240717 (EN)

Application
EP 18192224 A 20180903

Priority
• KR 20170113439 A 20170905
• KR 20180101576 A 20180828

Abstract (en)
[origin: EP3451396A1] A semiconductor device package includes a resin unit (410) having a first through hole (411) and a second through hole (412), a conductive body disposed on the resin unit (410) and having a cavity (11) that is concave in a direction from a top surface of the conductive body toward an outer bottom surface (12) thereof, and a light-emitting device disposed in the cavity (11), wherein the conductive body includes a first protrusion (12a-1) and a second protrusion (12b-1), which protrude in the direction toward the outer bottom surface (12) of the conductive body, and the first protrusion (12a-1) is disposed inside the first through hole (411), the second protrusion (12b-1) is disposed inside the second through hole (412), and a top surface of the resin unit (410) is in contact with a bottom surface of grooves (14a, 14b, 19a, 19b) that are formed in the conductive body to surround the outer bottom surface (12) of the conductive body.

IPC 8 full level
H01L 33/62 (2010.01); **H01L 33/64** (2010.01); **H01L 33/48** (2010.01); **H01L 33/60** (2010.01)

CPC (source: CN EP US)
H01L 33/52 (2013.01 - CN); **H01L 33/62** (2013.01 - EP US); **H01L 33/64** (2013.01 - CN); **H01L 33/647** (2013.01 - EP US); **H01L 33/486** (2013.01 - EP US); **H01L 33/60** (2013.01 - EP US); **H01L 2933/0033** (2013.01 - EP US)

Citation (examination)
• DE 102014103034 A1 20150910 - OSRAM OPTO SEMICONDUCTORS GMBH [DE]
• US 2015243864 A1 20150827 - AHN BUM MO [KR], et al
• JP 2003168828 A 20030613 - CITIZEN ELECTRONICS

Cited by
CN113451482A; US2021305465A1; US11715817B2

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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